

Electronic Patent Application Fee Transmittal

Application Number:	10826800			
Filing Date:	15-Apr-2004			
Title of Invention:	WAFER BONDING USING REACTIVE FOILS FOR MASSIVELY PARALLEL MICRO-ELECTROMECHANICAL SYSTEMS PACKAGING			
First Named Inventor/Applicant Name:	Tanya Jegeris Snyder			
Filer:	John Ray Pessetto/Rhonda Smyth			
Attorney Docket Number:	10030280-4			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appt Issue fee	1501	1	1400	1400
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Total in USD (\$)				1700